

### **IN THE CLAIMS**

Please amend the claims as follows:

Claims 1-11. (Canceled)

12. (Currently Amended) A system for in-circuit socket testing comprising:

a module, the module containing at least two switching devices, the module electrically attachable to a socket;

a printed circuit board, the printed circuit board containing a footprint for insertion of all pins of the socket; and

a test fixture, the test fixture being electrically connected to all pins of the socket through the printed circuit board, the test fixture supplying power and ground to power pins and ground pins of the socket,

wherein open connections to pins of the socket are detected by monitoring the pins after at least one of connecting a signal pin to a ground pin through one at least two switching devices and connecting a signal pin to a power pin through another at least two switching devices, and wherein the test fixture controls a first control signal and a second control signal, the first control signal controlling the one at least two switching devices to connect a signal pin to a ground pin, the second control signal controlling the another at least two switching devices to connect the signal pin to a power pin.

13. (Original) The system according to claim 12, wherein the at least two switching devices comprise field-effect transistors (FETs).

14. (Original) The system according to claim 12, wherein the socket comprises one of a pinned grid array (PGA) and a ball grid array (BGA).

15. (Original) The system according to claim 12, wherein the printed circuit board includes test points, the test fixture being electrically connected to the pins of the socket through the test points on the printed circuit board.

**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

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Title: Method and Apparatus for In-Circuit Testing of Sockets

Assignee: Intel Corporation

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Claims 16-20. (Canceled)